HSB-668I

Thermal Image Analysis Report

Report No:06I080001

Release Date: 03 / 03 / 2006

2006-03-03	Wenyuan Yang	Andrew Ku
Issue Stamp	**Manager**	**Test Engineer**

Thermal Image Analysis

Ⅰ. Model Name: HSB-668I A0.2

Ⅱ. Description: VIA Corefusion ISA Half-Size SBC

Ⅲ. Date: 03/ 03 / 2006

Ⅳ. Measure Site: AAEON QE Dept.

Ⅴ. Issued by: Andrew Ku

Ⅵ.Equipment:

1. TVS-100 series by NIPPON AVIONICS CO., LTD.

Ⅶ. Simulation Environment:

- **Temperature:**
  - Component Side – 1: 22.1degrees C
  - Component Side – 2: 24.1 degrees C
- **System Configuration :**
  - BIOS ver :0.6a
  - CPU: VIA C3 533A MHz (133x4.0)
  - Memory: KINGMAX / KSV684T4A2A-07L / PC-133 /256MB
  - HDD: MAXTOR 80GB
- **Application Software: Windows 2000 run HCT9.5**
- **Take Picture Time: Power on 2 hours after**

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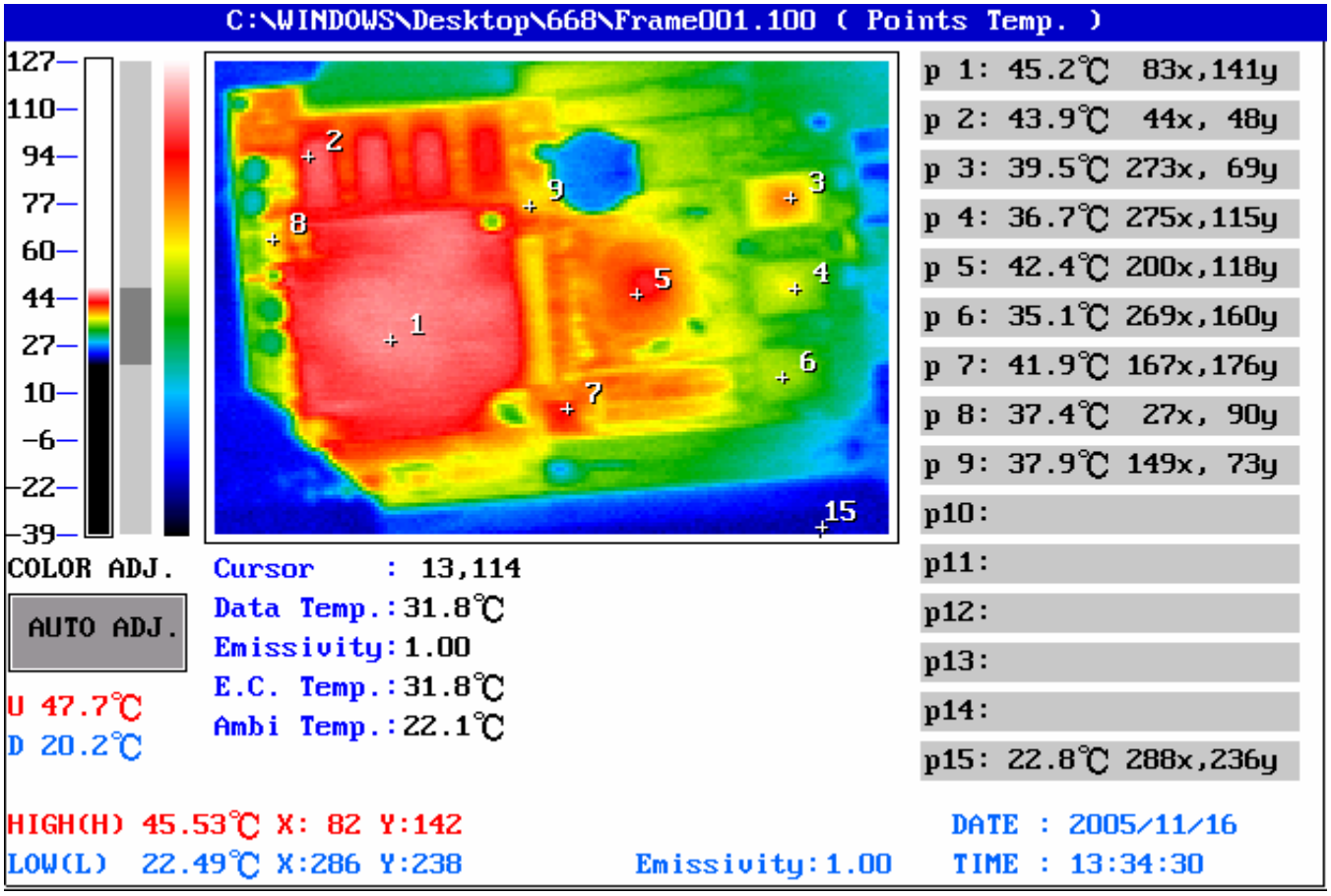
Thermal Image Analysis

Temperature Profile Test:

Component Side – 1:



Point	Position	Describe	Tc	Tm (25℃)	Tm (60℃)	Note
1	U19	VIA CPU.BGA 686P.Mark 533MHz.0.9V	-0℃~85℃	45.2℃	80.2℃	
2	U4	SDRAM.16M*16.PC-133TSOPII.54P.3.3V.HYNIX.HY57V561620CTP-H		43.9℃	78.9℃	
3	U12	PCI 32bit. Gigabit Ethernet Chip.REALTEK.RTL8110S-32	-30℃~100℃	39.5℃	74.5℃	
4	U20	PCI Ethernet Chip 10/100BaseT.REALTEK.RTL8100C-LF	-30℃~100℃	36.7℃	71.7℃	
5	U18	(TF)IC.SMD.BGA South Bridge.VIA.VT82C686BG	-25℃~150℃	42.4℃	77.4℃	
6	U24	128P QFP SuperI/O.WINBOND.W83977ATF-AW		35.1℃	70.1℃	
7	U25	GAL.PLCC.16V8.CS:35CB.Address decoder for SSD.		41.9℃	76.9℃	
8	C37	Pinlength=3.5mm.NIPPON CHEMI-CON.KMG10VB470M		37.4℃	72.4℃	
9	U13	SOT-143 4P.Supervisory Circuit.ANALOG DEVICES.ADM811SARTZ	-10℃~110℃	37.9℃	72.9℃	
10			-			
11						
12						
13						
14						
15		Ambient Temperature		22.1℃		

1.Tm (Measured operation temperature) must less than Tc (specified case Temperature) +5 degree ℃
2.Any Tm value showed in red words which meaning the value over the TC +5 degree ℃ of this device specification .

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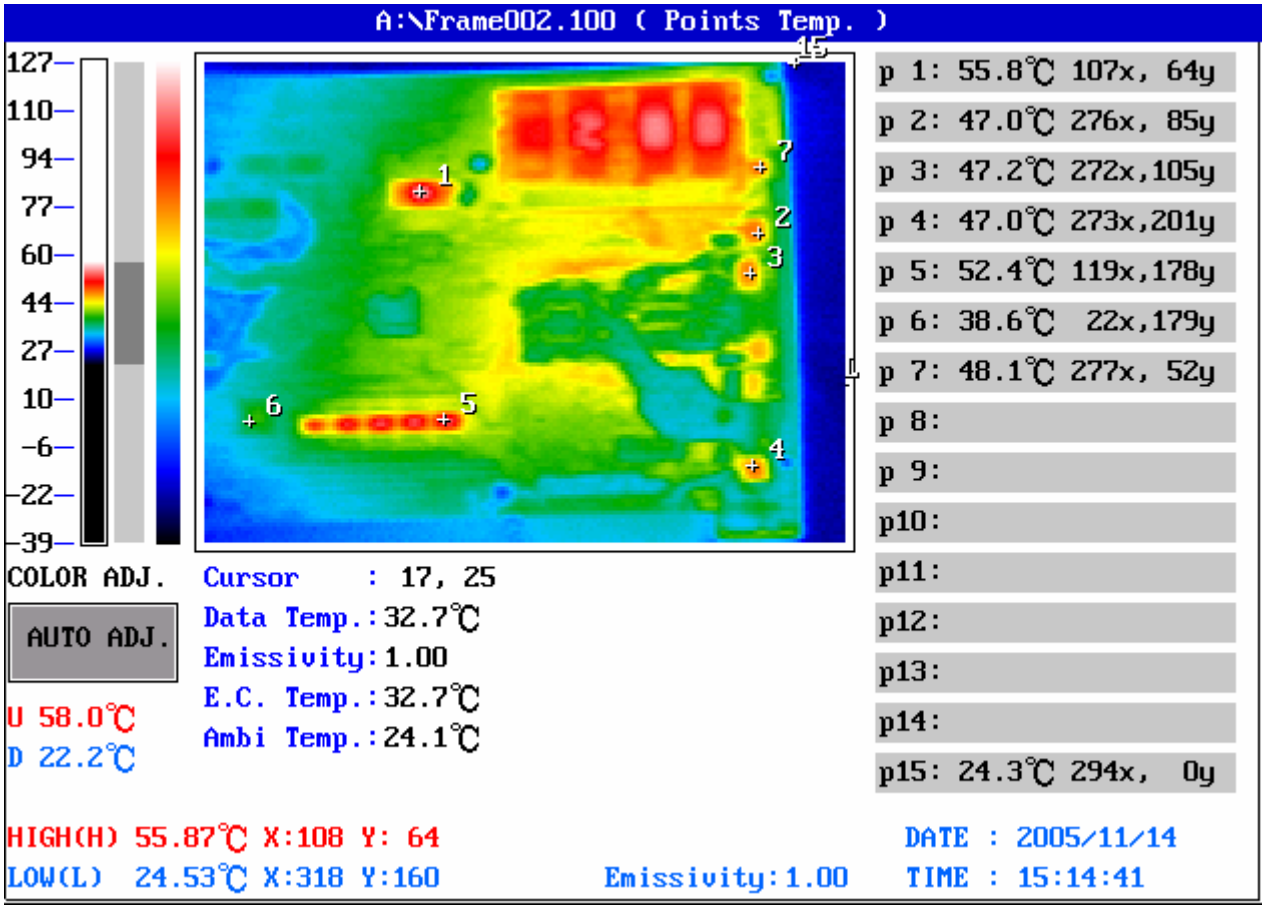
Component Side –2:



Point	Position	Describe	Tc	Tm (25℃)	Tm (60℃)	Note
1	U34	SSOP 48Pin.Clock gen.ICS.ICS94241AFLF	-30℃~100℃	55.8℃	90.8℃	
2	Q9	TO-252.N-Channel PowerMosfet.ON SEMI.NTD78N03T4G	-25℃~150℃	47.0℃	82.0℃	
3	Q10	TO-252.N-Channel PowerMosfet.ON SEMI.NTD60N02RT4G	-25℃~150℃	47.2℃	82.2℃	
4	Q14	TO-252.N-Channel PowerMosfet.ON SEMI.NTD78N03T4G	-25℃~150℃	47.0℃	82.0℃	
5	U38	IC.SSOP.TI.74F245	-30℃~100℃	52.4℃	87.4℃	
6	U37	TQFP 44P.CS:C5E4Ch.GENE-6310.LATTICS.M4A3-64/32	-30℃~100℃	38.6℃	73.6℃	
7	U32	SOP.8Pin Switching PWM Controller.IR.IRU3037CSPbF	-25℃~150℃	48.1℃	83.1℃	
8						
9						
10						
11						
12						
13						
14						
15		Ambient Temperature		24.1℃		

1.Tm (Measured operation temperature) must less than Tc (specified case Temperature) +5 degree ℃
2.Any Tm value showed in red words which meaning the value over the TC +5 degree ℃ of this device specification .

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